

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC080N03LS G	**Issued**	21. August 2021
MA#	MA001321316		
Package	PG-TDSON-8-5	**Weight***	123.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	0.65	0.65	6505	6505
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	iron	7439-89-6	0.038	0.03		306	
	non noble metal	copper	7440-50-8	37.762	30.56	30.60	305558	305956
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	477	477
encapsulation	organic material	carbon black	1333-86-4	0.097	0.08		785	
	plastics	epoxy resin	-	6.891	5.58		55758	
	inorganic material	silicondioxide	60676-86-0	41.538	33.60	39.26	336119	392662
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11746	11746
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1339	1339
solder	non noble metal	tin	7440-31-5	0.022	0.02		180	
	noble metal	silver	7440-22-4	0.028	0.02		225	
	non noble metal	lead	7439-92-1	1.060	0.86	0.90	8578	8983
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		181	
	non noble metal	copper	7440-50-8	22.292	18.04	18.07	180378	180613
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	iron	7439-89-6	0.011	0.01		92	
	non noble metal	copper	7440-50-8	11.320	9.16	9.17	91599	91719
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com